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(12) **United States Design Patent**
Tosto et al.

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- (54) **MODULAR PROBE**
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- (**) Term: **15 Years**
- (21) Appl. No.: **29/529,932**
- (22) Filed: **Jun. 11, 2015**

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(Continued)

Related U.S. Application Data

- (63) Continuation of application No. 29/484,162, filed on
Mar. 6, 2014, now Pat. No. Des. 734,271.
- (51) **LOC (10) Cl.** **13-03**
- (52) **U.S. Cl.**
USPC **D13/147**
- (58) **Field of Classification Search**
USPC D13/101, 110, 118, 123, 133, 146, 147,
D13/154, 184, 199; 307/150, 152;
361/600, 601, 622, 730, 796, 809;
439/62, 79, 260, 329, 395, 422, 499
CPC H01R 12/79; H01R 12/88
See application file for complete search history.

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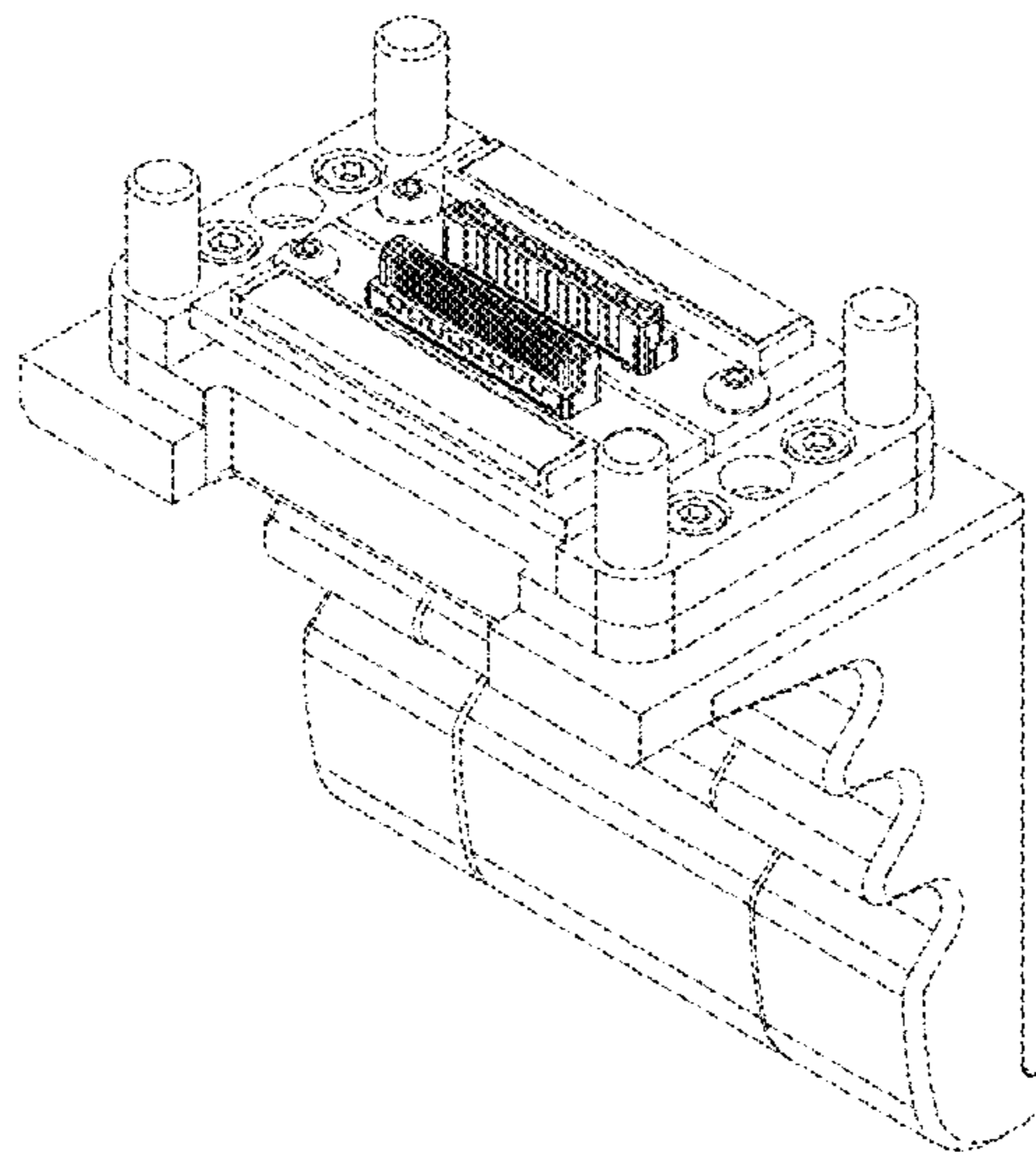
(57) **CLAIM**

The ornamental design for a modular probe, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a modular probe showing our new design;
 FIG. 2 is a front elevation thereof;
 FIG. 3 is a right elevation thereof;
 FIG. 4 is a top plan view thereof;
 FIG. 5 is a back elevation thereof; and,
 FIG. 6 is a left elevation thereof.
 The broken lines shown represent unclaimed subject matter and form no part of the claimed design.

1 Claim, 6 Drawing Sheets



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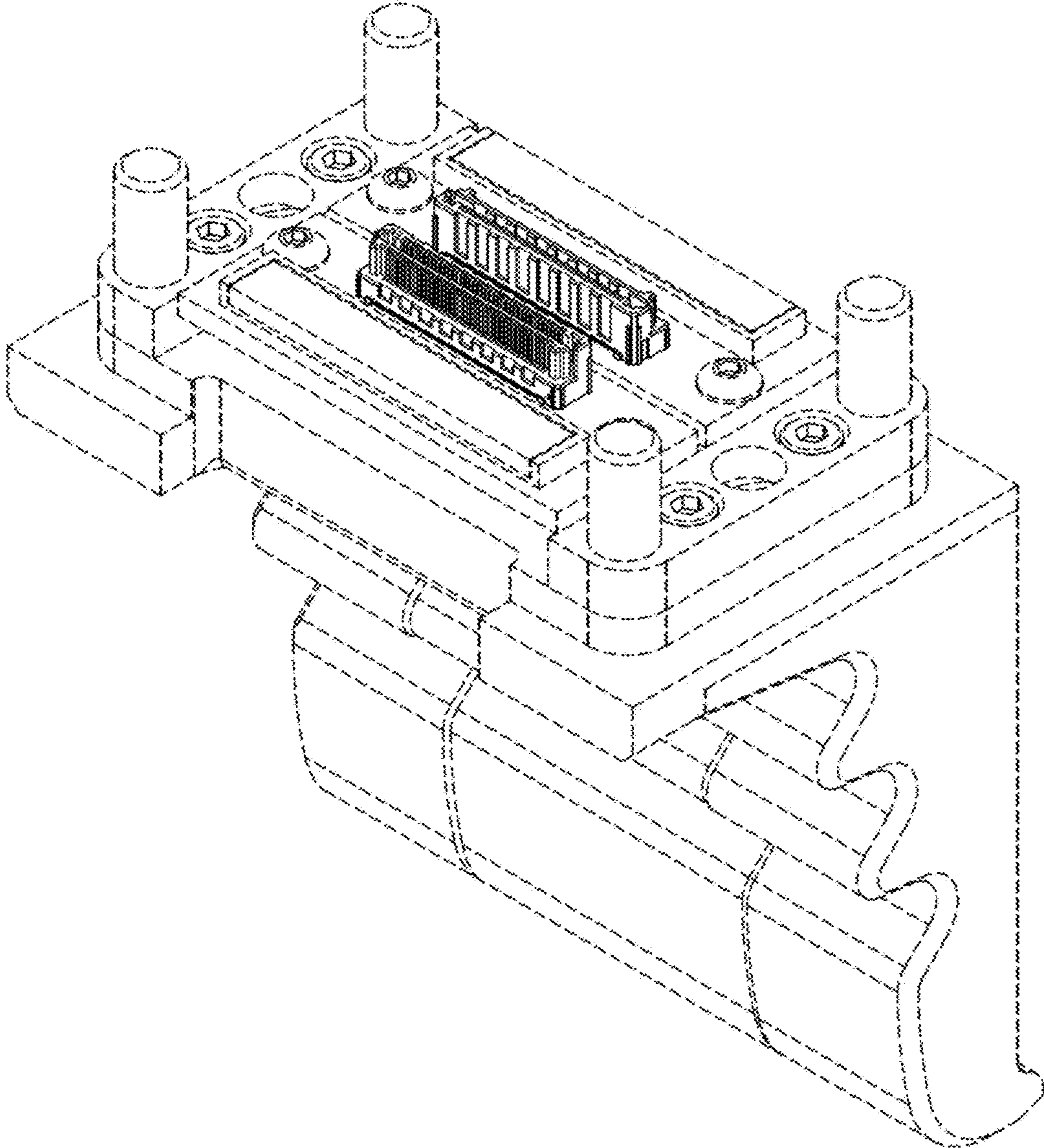


FIG. 1

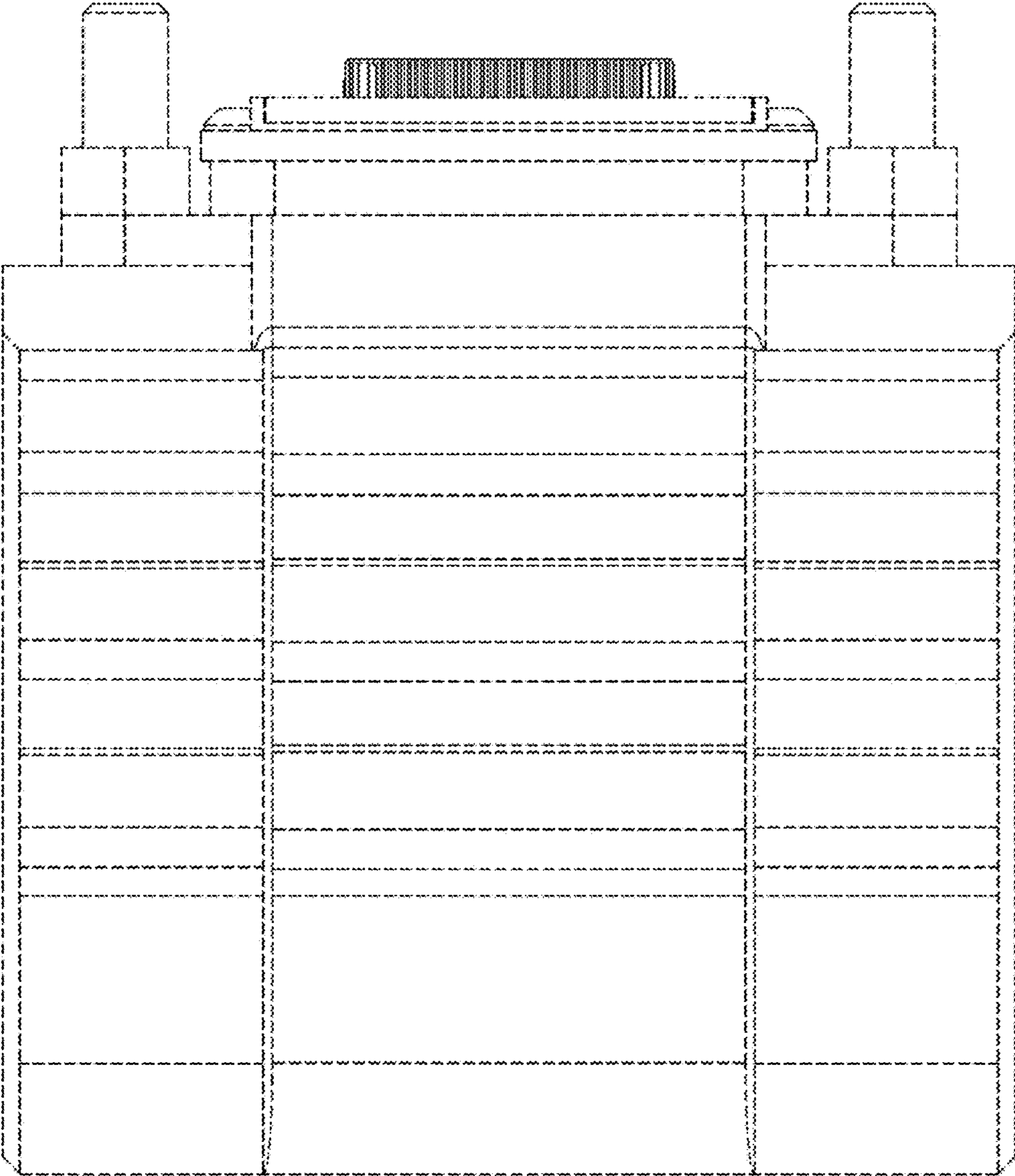


FIG.2

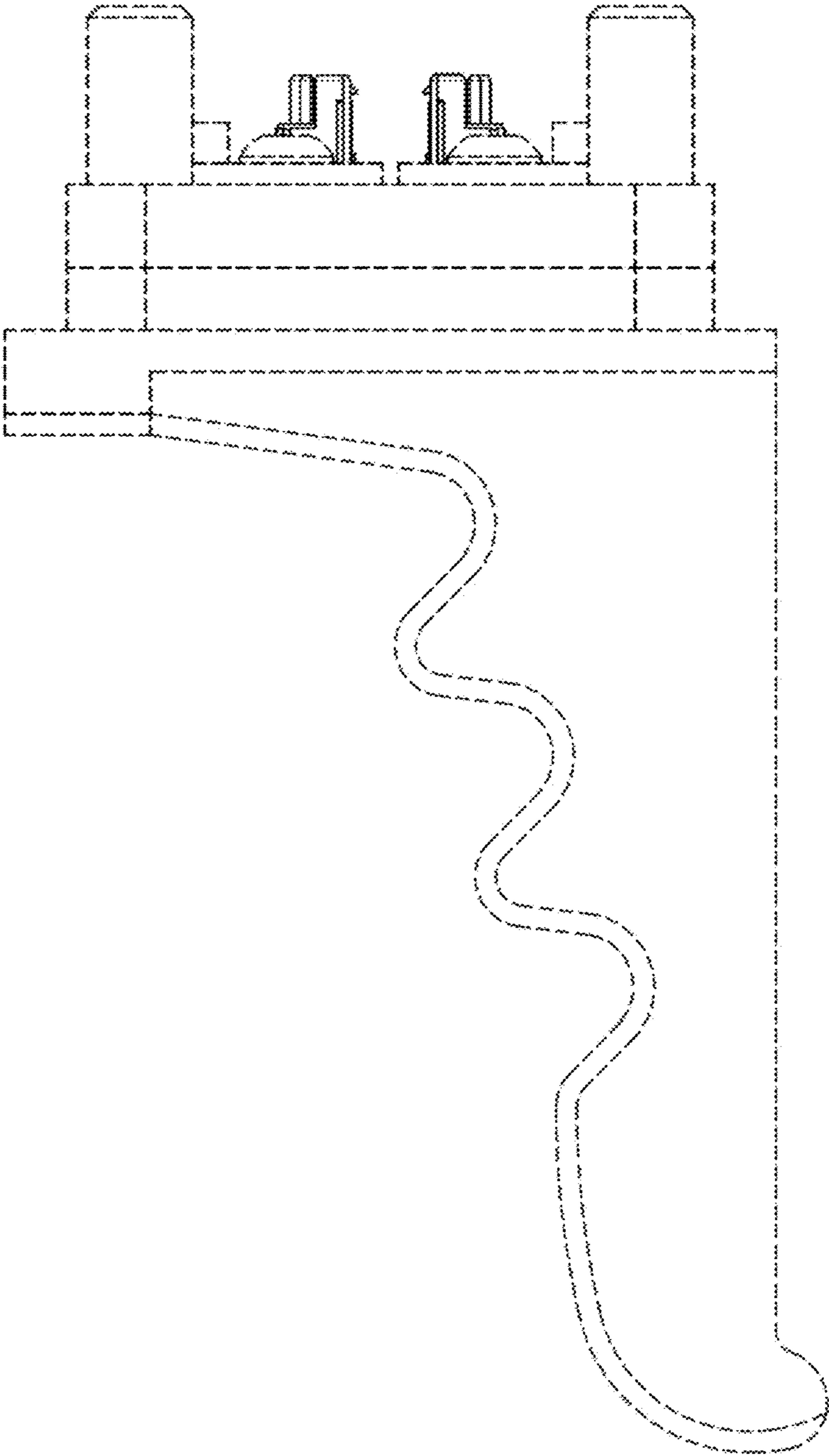


FIG. 3

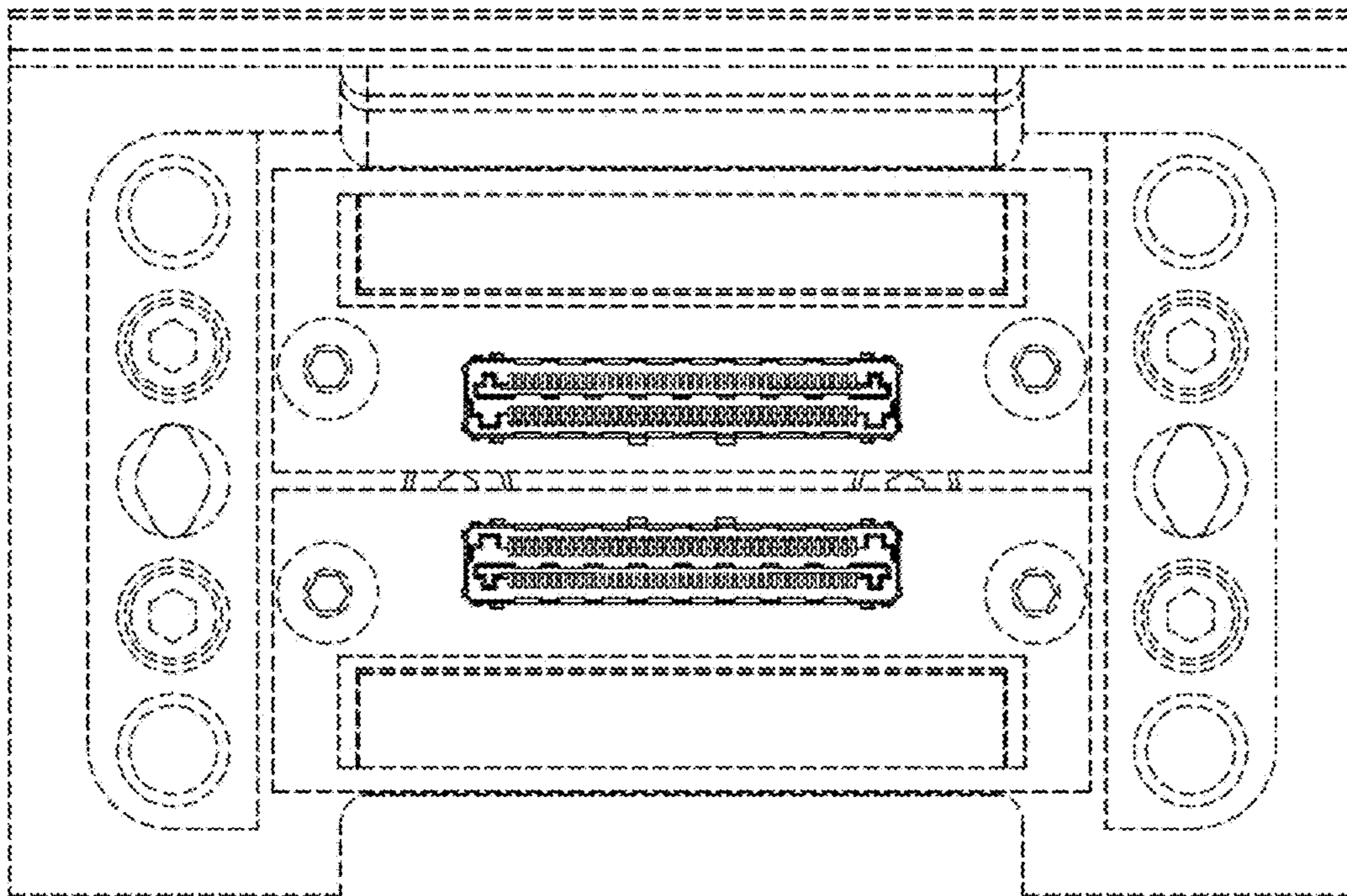


FIG. 4

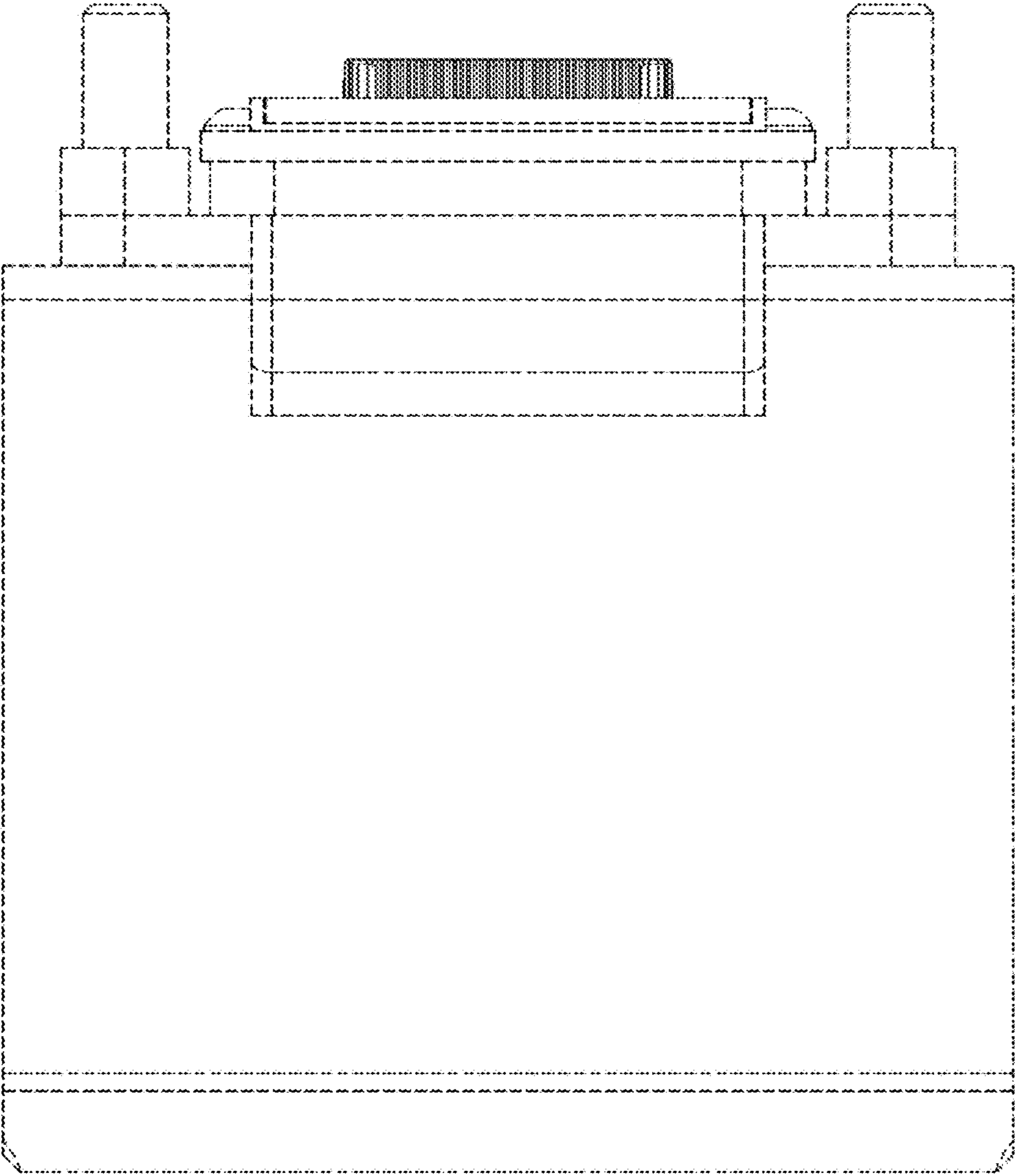


FIG. 5

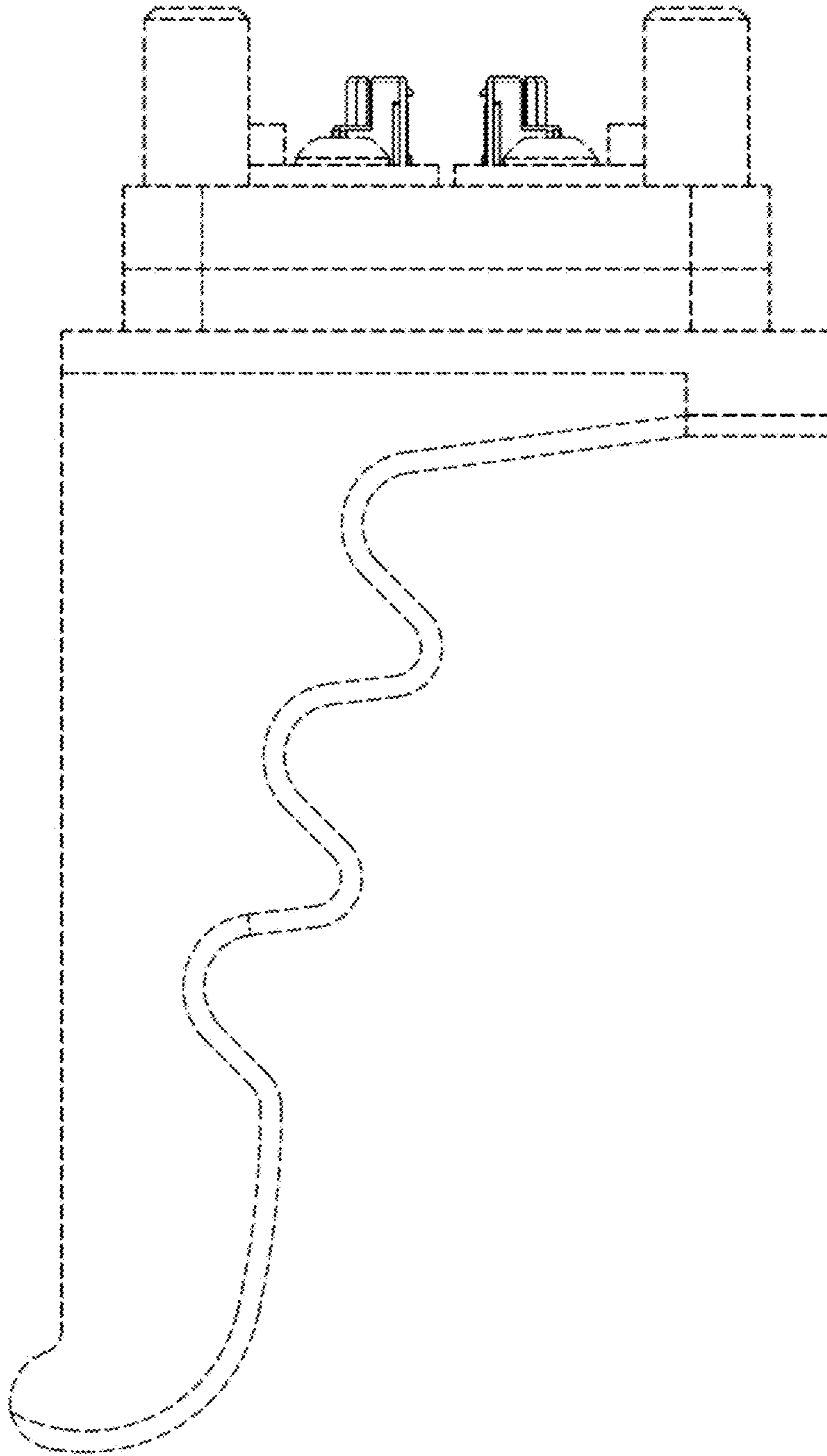


FIG. 6